

ISL73006SLHDEMO1Z

The ISL73006SLHDEMO1Z demonstration board (Figure 3) features the ISL73006SLH buck regulator. This IC is a small footprint radiation hardened POL designed for critical low-power applications.

The ISL73006SLH is operational over 3V to 18V, integrating high-side and low-side power FETs and switches at a default 500kHz frequency. The ISL73006SLH uses constant-frequency peak current mode control architecture for fast loop transient response. The ISL73006SLH can use its internal compensation or an external Type II compensation to stabilize the loop as determined by specific design and performance requirements.

By integrating both P-channel and N-channel power devices and with the option of internal compensation, a minimum of external components are required, thereby reducing the BOM count and complexity of the design.

The ISL73006SLHDEMO1Z demonstration board and this accompanying manual provide a quick and easy method to evaluate the ISL73006SLH part in the internal compensation configuration.

See the *ISL73006SLH Datasheet* for information about the operation, function, and performance of the device.

**Features**

- Optimized for 5V to 1.2V conversion using the internal slope and compensation configuration
- 1A output current

**Specifications**

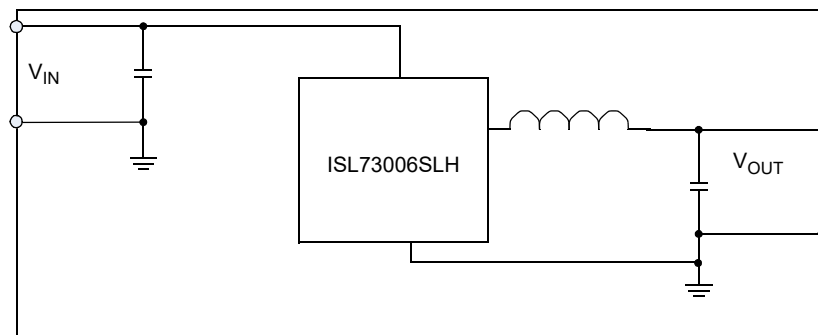
The ISL73006SLHDEMO1Z demonstration board is set up with the internal control loop compensation and slope configuration.

The board allows other conditions to be evaluated with user modification of component values but not external control loop or slope configuration.

Table 1 shows the electrical ratings of the ISL73006SLHDEMO1Z demonstration board.

**Table 1. Electrical Ratings**

Parameter	Rating
PVIN Supply Voltage	4V - 8V
DC Output Voltage	1.2V
Operating Frequency	500kHz
Output Current	1A
Temperature	-55°C to +125°C



**Figure 1. Block Diagram**

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# 1. Functional Description

The ISL73006SLHDEMO1Z demonstration board is configured by default for internal control loop and slope and optimized for 5V to 1.2V conversion with a 1A maximum output current. It contains the ISL73006SLH voltage regulator IC. [Figure 1](#) shows the ISL73006SLHDEMO1Z demonstration board block diagram. [Figure 3](#) and [Figure 4](#) show the ISL73006SLHDEMO1Z board images.

The ISL73006SLHDEMO1Z demonstration board provides access to critical pins of the IC device and convenient pads for connecting test equipment. For more information, see the schematic ([Figure 5](#)), PCB layers ([Figure 6](#) through [Figure 11](#)), and [Bill of Materials](#). [Figure 12](#) through [Figure 17](#) show the performance data using the ISL73006SLHDEMO1Z and basic lab equipment.

## 1.1 Operational Characteristics

The ISL73006SLHDEMO1Z only requires a single voltage supply > 4V connected to the PVIN pad to operate, outputting 1.2V on the VOUT pad with a 1A output current capability. Configured for a nominal PVIN voltage of 5V, the input operating voltage at which the IC turns on is set by the resistor divider ( $R_1$  and  $R_2$ ) on the ENABLE pin. The operating ripple current was chosen to be approximately 1/3 of the 1A-rated output current at a high 8V VPIN, resulting in a 6.8 $\mu$ H inductor.

*Note:* Do not exceed 5V on the ENABLE pin.

## 1.2 Setup and Configuration

The following equipment is recommended for testing the board:

- 5V power supply
- 100MHz oscilloscope

Complete the following steps to configure and use the board:

1. Configure the board as shown in [Figure 2](#).
2. Connect and turn on a 5V power supply to the PVIN pad.
3. Use the oscilloscope to look at VIN and VOUT waveforms and observe the behavior of the LX phase node located on pin 10 of the IC package. Proper probe grounding must be practiced when observing switching waveforms.
4. Output current loading can be externally added at the VOUT and GND pads for loaded output evaluations. A DVM(s) can monitor the input and output voltages and currents.

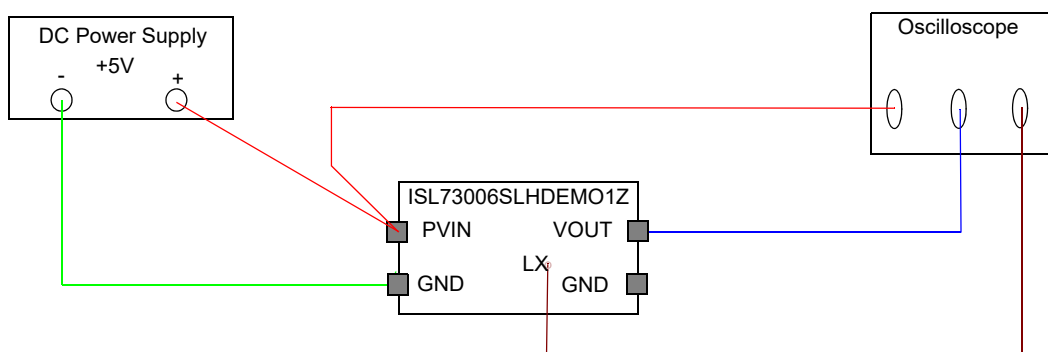


Figure 2. ISL73006SLH Basic Evaluation Test Setup Block Diagram

## 2. Board Design

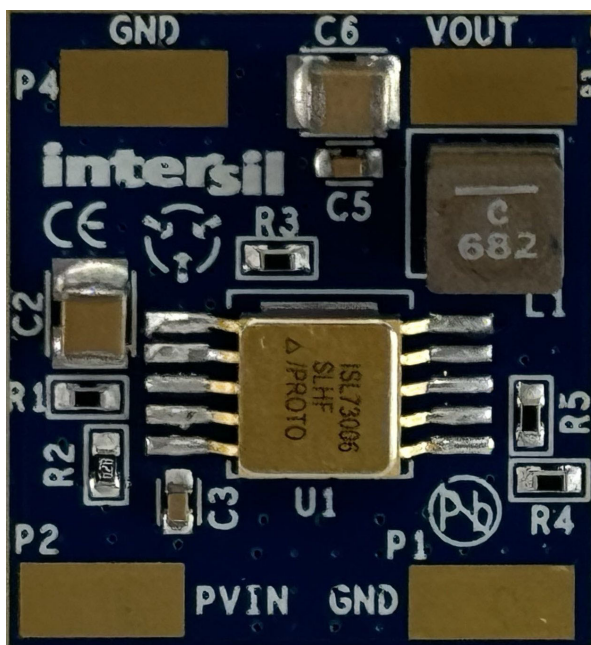


Figure 3. ISL73006SLHDEMO1Z Demonstration Board (Top)



Figure 4. ISL73006SLHDEMO1Z Demonstration Board (Bottom)

## 2.1 Basic Layout

The ISL73006SLH is located in the lower center of the board and is labeled U1. Connect the input power across the PVIN and GND jacks. The output voltage appears across the VOUT and GND jacks.  $C_{IN}$  is provided by  $C_1$  and  $C_2$ . The output LC filter is comprised of the  $L_{OUT}$ ,  $L_1$ , and  $C_{OUT}$  is provided by  $C_6$  and  $C_7$ . The EN threshold to enable the IC when PVIN is ~4V and is set by  $R_1$  and  $R_2$ . Consult the schematic in (Figure 5) for details.

## 2.2 Layout Guidelines

PCB design is critical to reducing parasitic inductances, with critical components being closely placed next to the IC. The critical components are the low ESR ceramic input capacitors. Avoid placing traces or components under the LX shapes to avoid noise coupling from the switching node.

## 2.3 Schematic Diagrams

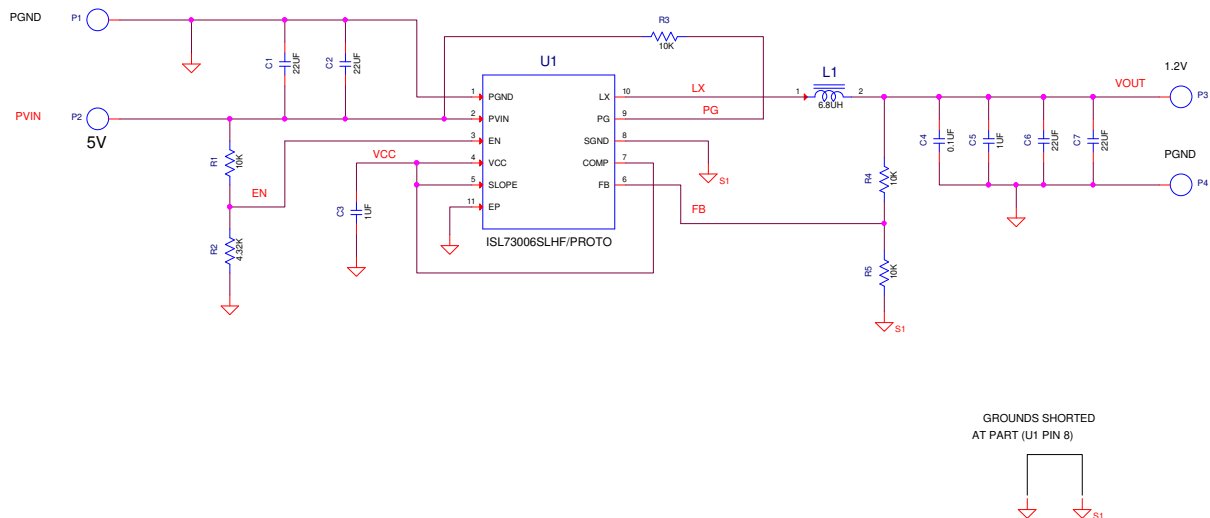


Figure 5. ISL73006SLHDEMO1Z Schematic

## 2.4 Bill of Materials

Reference Designator	Description	Manufacturer	Manufacturer Part
U1	IC-RAD HARD 1A POL REGULATOR	Renesas Electronics	ISL73006SLHF/PROTO
L1	COIL-PWR INDUCT, SMD, 5.4×5.2mm, 6.8µH.20%, 6A, 27mΩ, ROHS	Coilcraft	XEL5050-682ME
C1, C2,	22µF, Multilayer Cap	Various	Generic
C3, C5	1µF, Multilayer Cap	Various	Generic
C4	0.1µF, Multilayer Cap	Various	Generic
C6, C7	22µF, Multilayer Cap	Various	Generic
R1, R3, R4, R5	10kΩ, Thick Film Chip Resistor	Various	Generic
R2	4.32kΩ, Thick Film Chip Resistor	Various	Generic

## 2.5 Board Layout

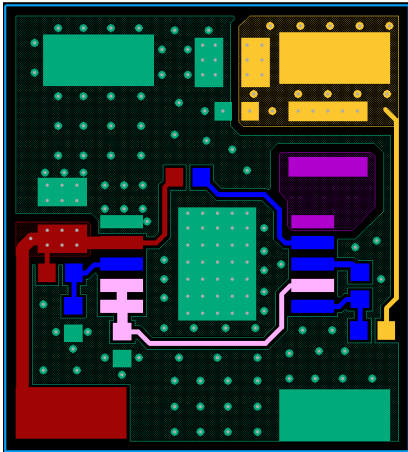


Figure 6. Top Layer

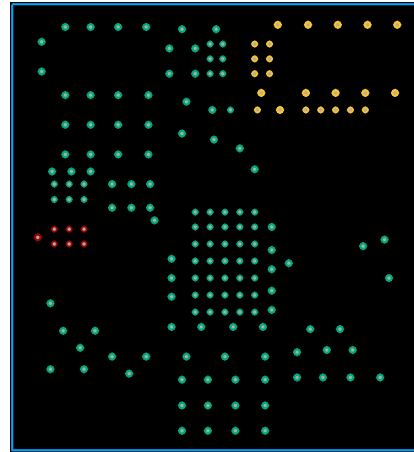


Figure 7. Layer 2

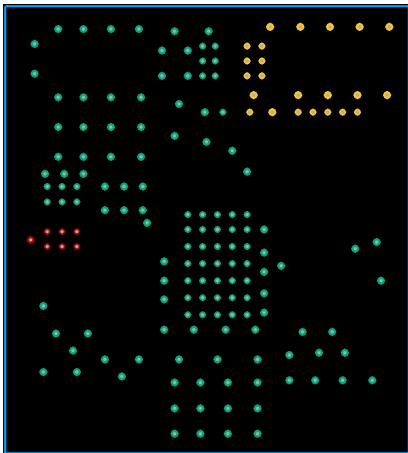


Figure 8. Layer 3

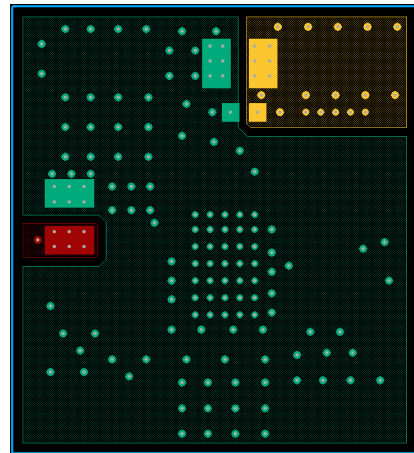


Figure 9. Bottom Layer

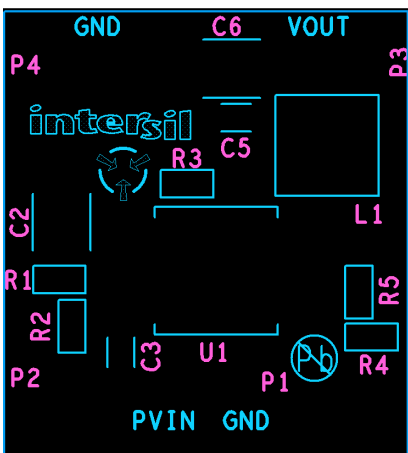


Figure 10. Top Assembly Layer

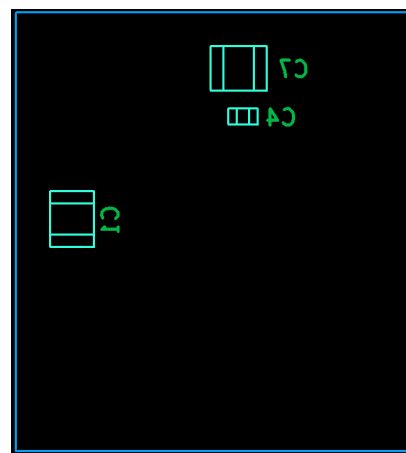


Figure 11. Bottom Assembly Layer

### 3. Typical Performance Graphs

Unless otherwise noted,  $P_{VIN} = 5V$ ;  $V_{OUT} = 1.2V$ ,  $T_A = \text{Room Ambient}$ , circuit modifications necessary

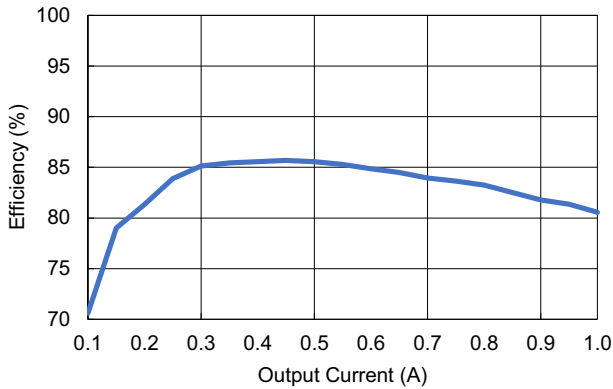


Figure 12. Efficiency vs Output Current

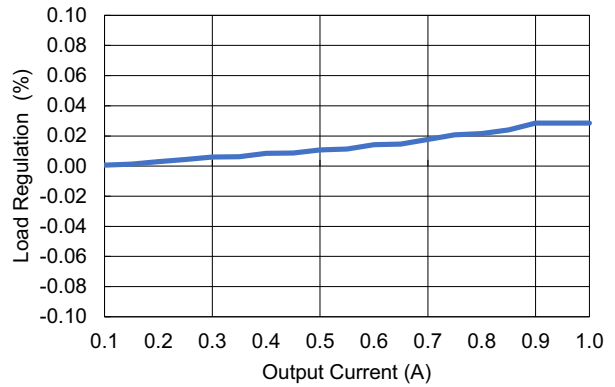


Figure 13. Load Regulation vs Output Current

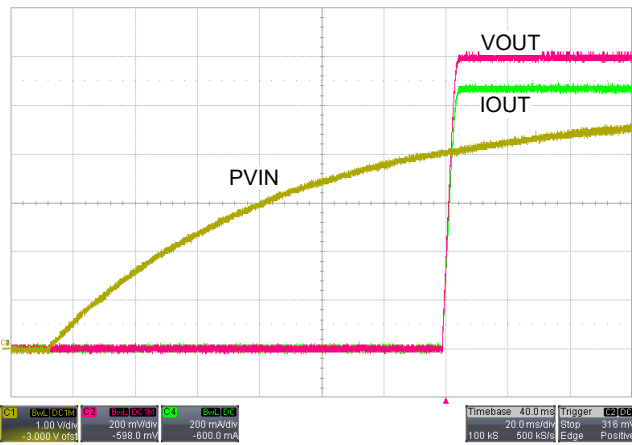


Figure 14. Turn-on by PVIN, 1.1Ω load

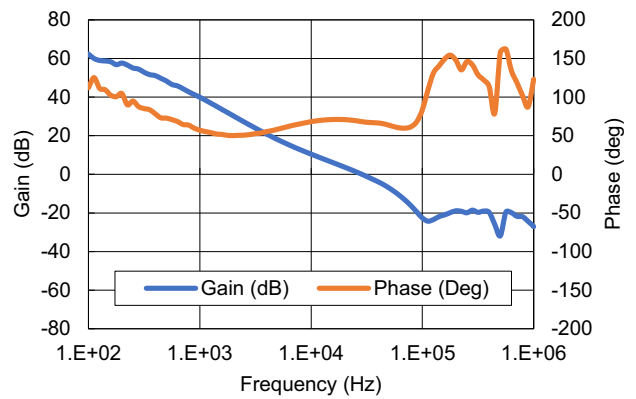


Figure 15. Gain/Phase BODE Plot,  $I_{OUT} = 0.5A$

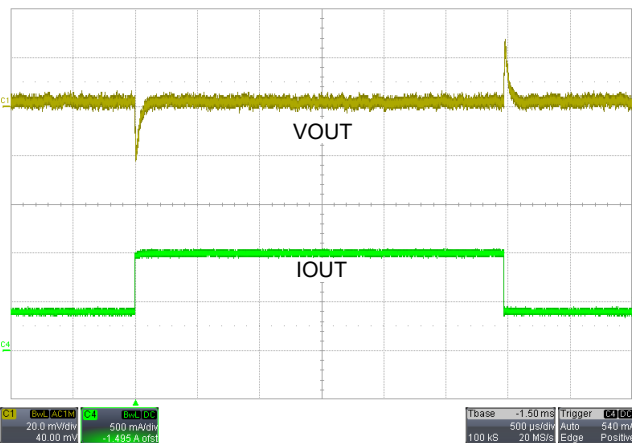


Figure 16. 0.6A Load Transient

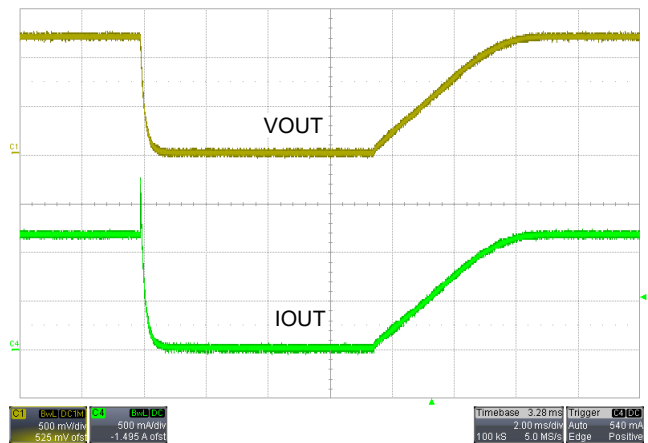


Figure 17. Positive Overcurrent Protection and Restart

## 4. Ordering Information

Part Number	Description
ISL73006SLHDEMO1Z	Radiation Hardened ISL73006SLH Buck Regulator, 5V <sub>IN</sub> to 1.2V <sub>OUT</sub> Internal Compensation and Slope Demonstration Board

## 5. Revision History

Revision	Date	Description
1.00	Dec 21, 2023	Initial release



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